

/ Descriptions

1A ABS/LBF
1A Surface Mount Glass Passivated Bridge Rectifier ABS/LBF thin package.

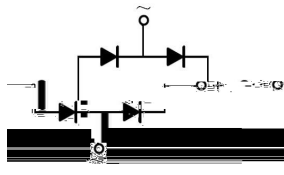
/ Features

Glass Passivated Chip Junction, Reverse Voltage :100 to 1000V,Forward Current: 1A,High Surge Current Capability, Designed for Surface Mount Application,HF Product.

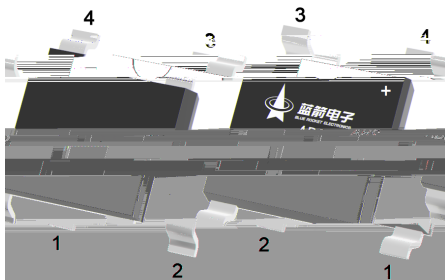
/ Applications

General purpose.

/ Equivalent Circuit



/ Pinning



PIN	DESCRIPTION
1	Input Pin (~)
2	Input Pin (~)
3	Output Anode (+)
4	Output Cathode (-)



/ Marking

See Marking Instructions.

/ Absolute Maximum Ratings(Ta=25)

Parameter	Symbol	Rating						Unit
		ABS1-10	ABS2-10	ABS4-10	ABS6-10	ABS8-10	ABS10-10	
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	100	200	400	600	800	1000	V
Average Rectified Output Current at $T_c=125\text{ }^{\circ}\text{C}$	I_o	1						A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	35						A
Typical Junction Capacitance Note1	C_i	13						pF
Typical Thermal Resistance Note2	$R_{\theta JA}$	72						/W
	$R_{\theta JC}$	20						/W
Operating and Storage Temperature Range	T_j, T_{stg}	-55~150						

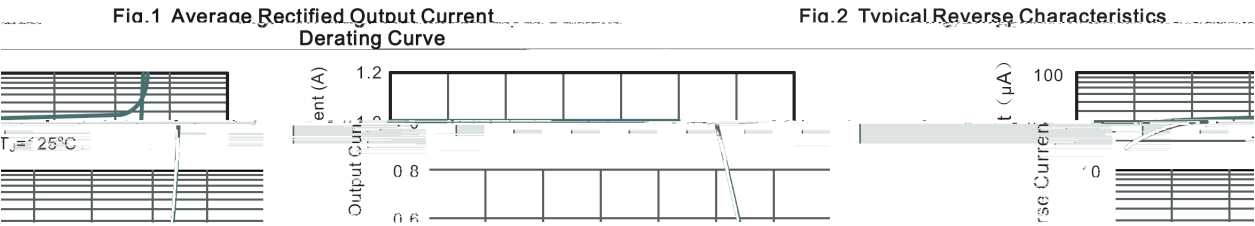
Note:

1. Measured at 1MHz and applied reverse voltage of 4 V D.C.
2. Mounted on glass epoxy PC board with 4 1.5" 1.5" 3.81 3.81 cm copper pad.

/ Electrical Characteristics(Ta=25)

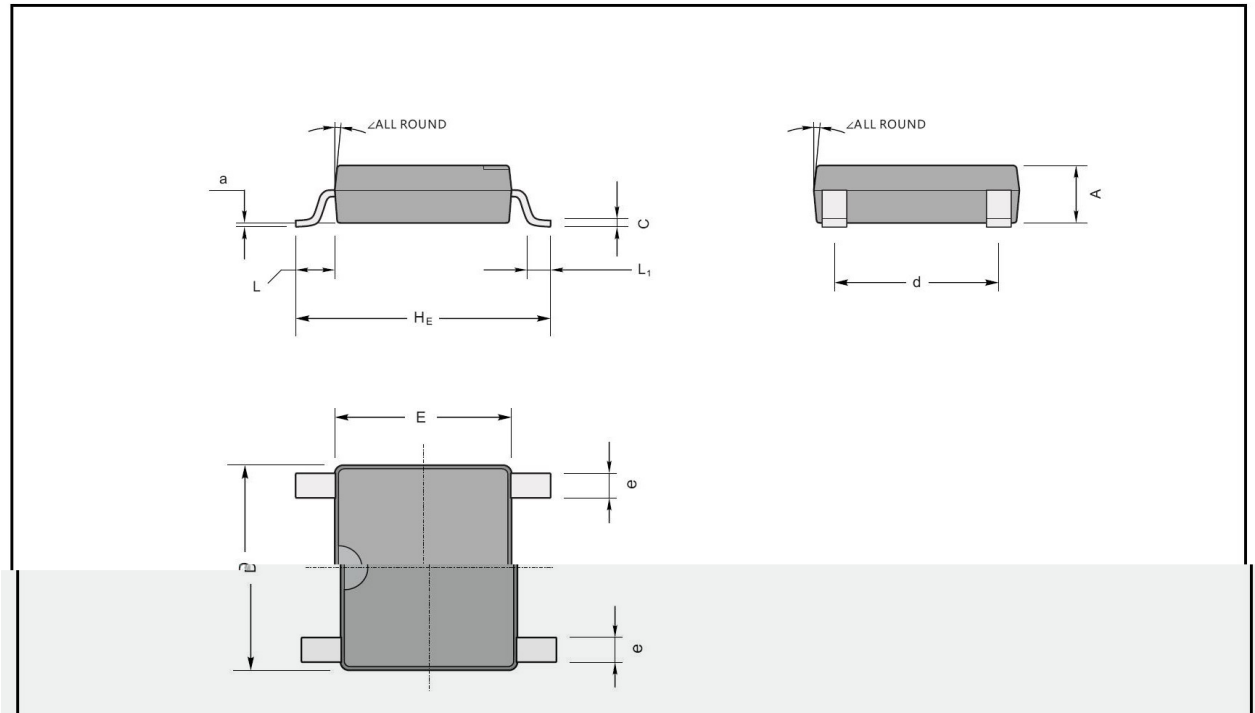
Parameter	Symbol	Test Conditions	Rating	Unit
Forward Voltage per element	V_F	$I_F=1A$	1.1	V
Maximum DC Reverse Current at Rated DC Blocking Voltage	I_R	$T_a=25$	5	μA
		$T_a=100$	50	
		$T_a=125$	100	

/ Electrical Characteristic Curve



/ Package Dimensions

ABS/LBF



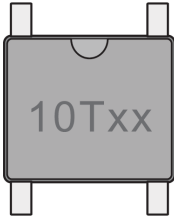
ABS/LBF mechanical data

UNIT	A	C	D	E	H _E	d	e	L	L ₁	a
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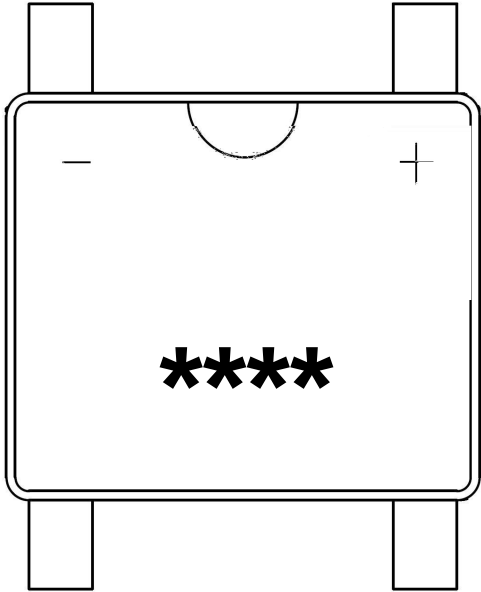
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/ Marking Instructions

Marking

Type number	Marking code
ABS1-10	10T1
ABS2-10	10T2
ABS4-10	10T4
ABS6-10	10T6
ABS8-10	10T8
ABS10-10	10T10
	

/ Marking Instructions



10T1

1 *

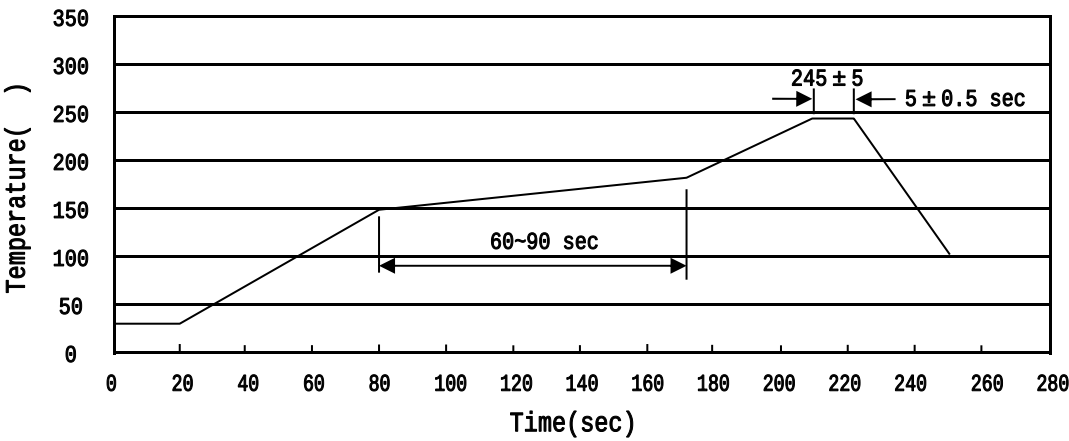
3 *

Note:

10T1 Product Type Code

**** Lot No. Code The 1st * means:YM Code The last 3 * means:little Lot No
Code

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- 1

150 180

60 90sec;

1.Preheating:150~180 , Time:60~90sec.
- 2

245 5

5 0.5sec;

2.Peak Temp.:245 5 , Duration:5 0.5sec.
- 3

2 10 /sec.

3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260 5 10 1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension (unit mm ³)		
ABS/LBF	5,000	2	10,000	7	70,000	13 ×12	336X336X40	380X335X366

/ Notices